

LAMINATED FIN HEAT SINK FOR ELECTRONIC DEVICES

Abstract of the Disclosure

A heat sink may transfer heat from electronic devices. A heat conductive base may have integrally attached thereto a plurality of parallel fins. The fins may be made up of
5 two sheets of material. One sheet may be a metal having significant structural integrity and the other sheet of material may be a pyrolytic graphite material having excellent heat transfer characteristics. The two layers may be integrally bonded together.